

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	100	bond\$3 near2 wire and (board shelf substrate) with (egde side) with plating with (layer strip) and (etching remov\$3) with (conductive plating layer)	USPAT; EPO; JPO	OR	ON	2005/06/08 14:09
L2	0	bond\$3 near2 wire and (board shelf substrate) with (egde side) with plating with (layer strip) and split\$4 with (conductive plating layer) with (hole via)	USPAT; EPO; JPO	OR	ON	2005/06/08 14:09
L3	6	bond\$3 near2 wire and (board shelf substrate) and (egde side) with plating with (layer strip) and (divid\$3 split\$4) with (conductive plating layer) with (hole via)	USPAT; EPO; JPO	OR	ON	2005/06/08 14:10
L4	23	(board shelf substrate) and (egde side) with plating with (layer strip) and (divid\$3 split\$4) with (conductive plating layer) with (hole via)	USPAT; EPO; JPO	OR	ON	2005/06/08 14:10
L5	3	("4638348"   "5006792"   "5672909").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/08 14:11
L6	11	("4410905"   "4839717"   "5008734"   "5173767"   "5225709"   "5294751"   "5329156"   "5343074"   "5402318"   "5457340"   "5497031").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/08 14:12
L7	5	("5008734"   "5214845"   "5225709"   "5227583"   "5294751").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/08 14:15
L8	2	("4396795"   "4925024").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/08 14:16
L9	3	("4922324"   "4972253"   "5043794").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/08 14:16
L10	61	("4972253").URPN.	USPAT	OR	ON	2005/06/08 14:17
S1	23	("4223321" "4891687" "0468270" "5089878" "5206986" "5218515" "5488257" "5491632" "5557502" "5625166" "5726860" "5777265" "5787575" "5801450" "5858816" "5877553" "5880529" "6008532" "6014809" "6020631" "6031283" "6073344" "6153829").PN.	USPAT; EPO; JPO	OR	ON	2005/06/07 18:29
S2	2	carapella.in. and circuit.ti.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/06/07 18:30

S3	4	("5491362"   "5557502"   "5877553"   "6008532").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/07 18:30
S4	1	bond\$3 near2 shelf with plat\$3 and conductive near2 strip	USPAT; EPO; JPO	OR	ON	2005/06/07 18:34
S5	8	bond\$3 near2 shelf with plat\$3	USPAT; EPO; JPO	OR	ON	2005/06/07 18:35
S6	50	bond\$3 near2 wire and shelf with plat\$3	USPAT; EPO; JPO	OR	ON	2005/06/07 18:41
S7	9	bond\$3 near2 wire and shelf with plating	USPAT; EPO; JPO	OR	ON	2005/06/07 18:49
S8	17	("3349480"   "4660063"   "4711026"   "4859807"   "5096849"   "5104684"   "5126532"   "5196376"   "5455998"   "5487218"   "5569398"   "5613858"   "5811019"   "5856636"   "5881455"   "5906042").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/07 18:42
S9	10	("4420767"   "4819041"   "4899118"   "5218515"   "5285352"   "5291062"   "5355283"   "5357672"   "5400220"   "5442852").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/07 18:46
S10	3	("5102829"   "5130889"   "5357672").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/07 18:48
S11	837	bond\$3 near2 wire and (egde side) with plating	USPAT; EPO; JPO	OR	ON	2005/06/07 18:49
S12	304	bond\$3 near2 wire and (board shelf substrate) with (egde side) with plating	USPAT; EPO; JPO	OR	ON	2005/06/07 18:49
S13	138	bond\$3 near2 wire and (board shelf substrate) with (egde side) with plating with (layer strip)	USPAT; EPO; JPO	OR	ON	2005/06/08 14:02
S14	1	"4223321".pn.	USPAT; EPO; JPO	OR	ON	2005/06/08 09:46